

Historical Information

Provided by: HIWIN TECHNOLOGIES CORP.

SEQ_NO	1	Date of announcement	2016/08/30	Time of announcement	16:04:03
Subject	The Company sign MoU with Etron Technologies Inc., Hiwin Mikrosystem Corporation and GlobalMEMS Co., Ltd.				
Date of events	2016/08/30	To which item it meets	paragraph 10		

Statement	<p>1.Date of occurrence of the event:2016/08/30</p> <p>2.Counterparty to the contract or commitment:Etron Technologies Inc., Hiwin Mikrosystem Corporation and GlobalMEMS Co., Ltd.</p> <p>3.Relationship to the Company:None</p> <p>4.Starting and ending dates (or rescission date) of the contract or commitment:2016/08/30</p> <p>5.Major content (not applicable where rescinded): Cross-industry MoU</p> <p>6.Restrictive covenants (not applicable where rescinded):None</p> <p>7.Effect on company finances and business (not applicable where rescinded): To accelerate and enhance the Company's technologies and power of service by the cooperation of Cross-industry supply chain, expand the market and promote the competitiveness globally.</p> <p>8.Concrete purpose/objective (not applicable where rescinded): The purpose of the MoU is to confirm bilateral side will upgrade skills, develop product and unite marketing based on the Internet of Things, Cloud Computing, Big Data and Intellectual Manufacturing with the trend and concept of Industry 4.0. Also, to accelerate and enhance the Company's technologies and power of service by the cooperation of Cross-industry supply chain, expand the market and promote the competitiveness globally.</p> <p>9.Any other matters that need to be specified:None.</p>
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